502129492 11/15/2012

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Timothy H. Daubenspeck	11/09/2012
Mark C.H. Lamorey	11/09/2012
Xiao Hu Liu	11/09/2012
Thomas M. Shaw	11/09/2012
Thomas A. Wassick	11/03/2012

RECEIVING PARTY DATA

Name:	International Business Machines Corporation	
Street Address: New Orchard Road		
City:	Armonk	
State/Country:	NEW YORK	
Postal Code:	10504	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13677373

CORRESPONDENCE DATA

4106301656 Fax Number:

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

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Address Line 4: ANNAPOLIS, MARYLAND 21401

ATTORNEY DOCKET NUMBER:	BUR920110194US1
NAME OF SUBMITTER:	Peter A. Balnave, Ph.D.
	PATENT

REEL: 029301 FRAME: 0137 502129492

This document serves as an Oath/Declaration (37 CFR 1.63). source=BUR920110194US1_Assignment-Declaration#page1.tif source=BUR920110194US1_Assignment-Declaration#page2.tif source=BUR920110194US1_Assignment-Declaration#page3.tif source=BUR920110194US1_Assignment-Declaration#page4.tif source=BUR920110194US1_Assignment-Declaration#page5.tif

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Total Attachments: 10

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PATENT REEL: 029301 FRAME: 0138

Title of Invention: ELASTIC MODULUS MAPPING OF AN INTEGRATED CIRCUIT CHIP IN A CHIP/DEVICE PACKAGE

As a below named inventor, I hereby declare that:
This declaration is directed to the attached application, or (if following box is checked):
United States application or PCT international application number
The above-identified application was made or authorized to be made by me.
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.
I have reviewed and understand the contents of the application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR Section 1.56.

Whereas, the undersigned inventor(s) has/have made certain inventions, improvements, and discoveries (herein referred to as the "Invention") disclosed in the above-identified patent application and further identified by the IBM Docket Number provided above in the header of this document;

Whereas, International Business Machines Corporation, a corporation of New York having a place of business at Armonk, New York (herein referred to as "IBM"), desires to acquire, and each undersigned inventor desires to grant to IBM, the entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications and patents directed thereto;

Each undersigned inventor acknowledges their prior and ongoing obligations to sell, assign, and transfer the rights under this Assignment to IBM and is unaware of any reason why they may not have the full and unencumbered right to sell, assign, and transfer the rights hereby sold, assigned, and transferred, and has not executed, and will not execute, any document or instrument in conflict herewith. Each undersigned inventor also hereby grants IBM, its successors, legal representatives, and assigns, the right to insert in this Assignment any further identification (including, but not limited to, patent Application Number) which may be necessary or desirable for recordation of this Assignment. This Assignment is governed by the substantive laws of the State of New York, and any disputes will be resolved in a New York state court or federal court cited in New York.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

(1) Legal Name of Inventor: Timothy H. Daubenspeck

Signature: Thirsthy H. Daubenspeck Date: November 9, 2012

Page 2 of 2

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(1) Legal Name of Inventor: Mark C.H. Lamorey

Signature: 125 / June 2

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(1) Legal Name of Inventor; Xiao Hu Liu

Signature: Carollulin

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(1) Legal Name of Inventor: Thomas M. Shaw

Signature: Shomae M. Slean Date: 11-09-2012

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(1)	Legal Name of Inventor: Thomas A. Wassick		
3	Signature: Thomas A. Wassick	Date:_	11/3/18

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